

Additional environmental conditions

Tensile strength of leads DIN IEC 68 T2-21 (Ua 1)
Flexibility of leads DIN IEC 68 T2-21 (Ub)
Sealing test A nicht dicht (not hermetically sealed)
Solderability DIN IEC 68 T2-20 (Ta) 100% RoHS compliant
Solvent resistance EN 60068-2-45, Test xA non-washable device

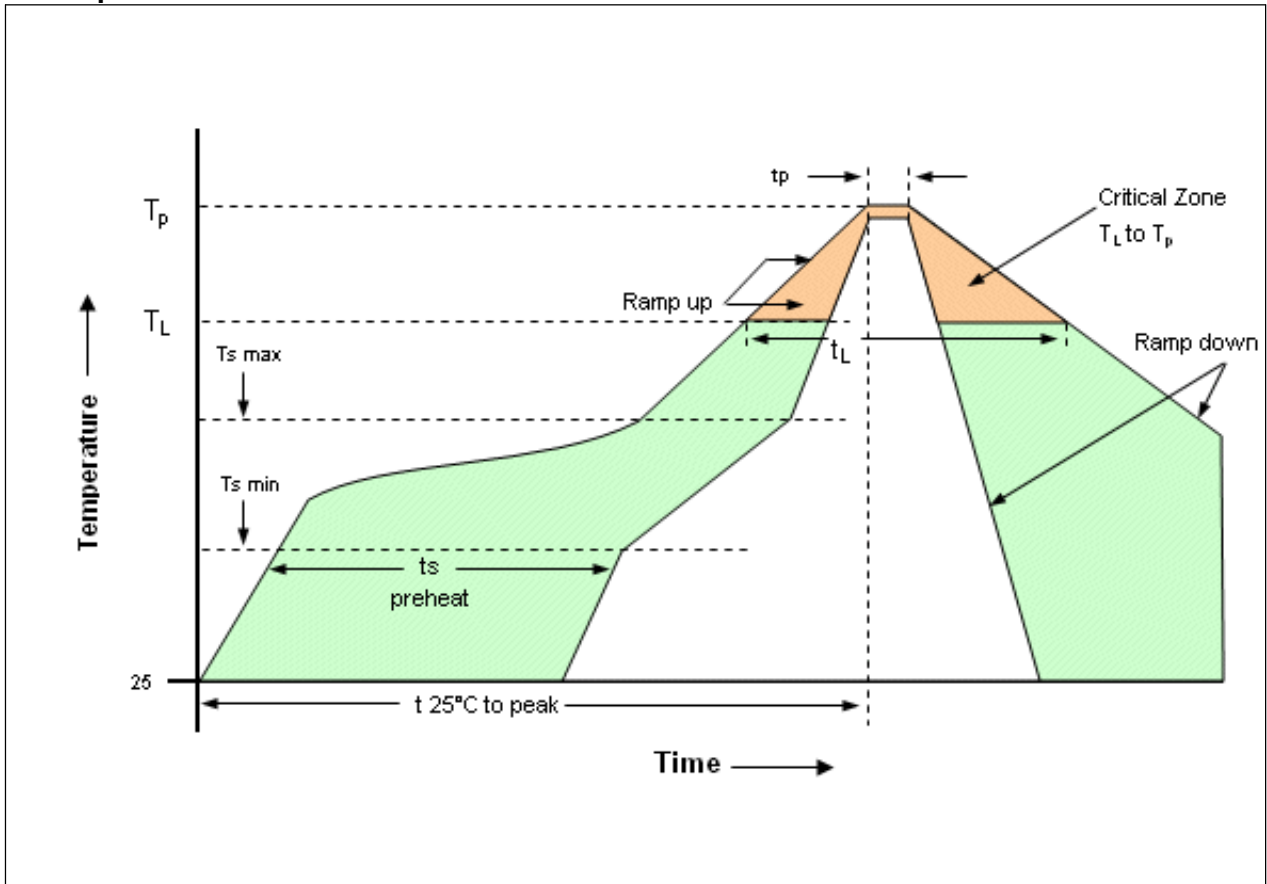
Absolute Maximum Ratings

Parameter	Min	Typ	Max	Units	Condition
Operable temperature range	-40		85	°C	
Storage temperature range	-50		90	°C	

Enclosure

Type G218B	Height 5.9 mm
<p style="text-align: right;">G 218</p>	
all units in mm	
<p>Pin Connections</p> <p>Pin 1: Vc (control voltage) Pin 2: Enable/Disable Pin 3: GND(Case) Pin 4: RF-Output Pin 5: RF-Output compl. Pin 6: Vs (supply voltage)</p>	
<p>Marking</p> <p>C5310A1-0187 245M760 * VI AYYWW * pin-1 marking</p>	

Reflow profile



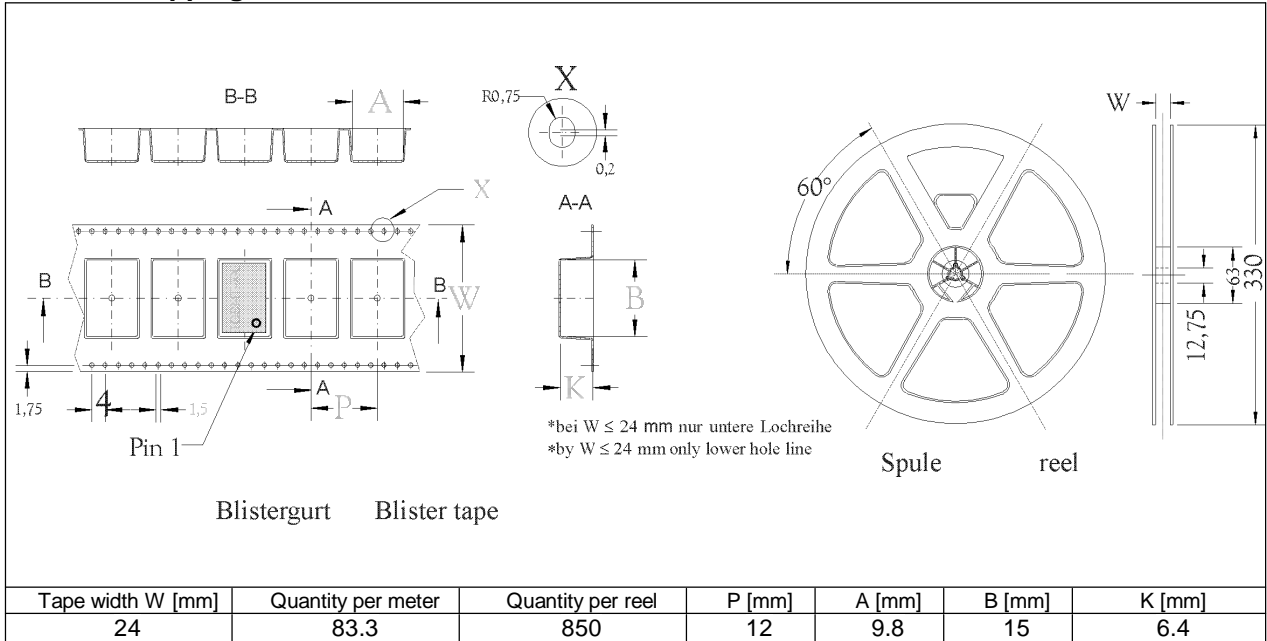
Profile Feature	Pb-Free Assembly/Sn-Pb Assembly
Average ramp-up rate (TL to Tp)	3°C/second max.
Preheat -Temperature Min (T _{smin})	150°C
-Temperature Min (T _{smax})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{smax} to TL - Ramp-up Rate	3°C/second max.
Time maintained above - Temperature (TL)	217°C
- Time (t _L)	60-150 seconds
Peak Temperature (T _p)	max 260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

Additional Information

This SMD oscillator has been designed for pick and place reflow soldering.
SMD oscillators must be on the top side of the PCB during the reflow process.

Standard shipping method



Notes:

Unless otherwise stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C).
Subject to technical modification.

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